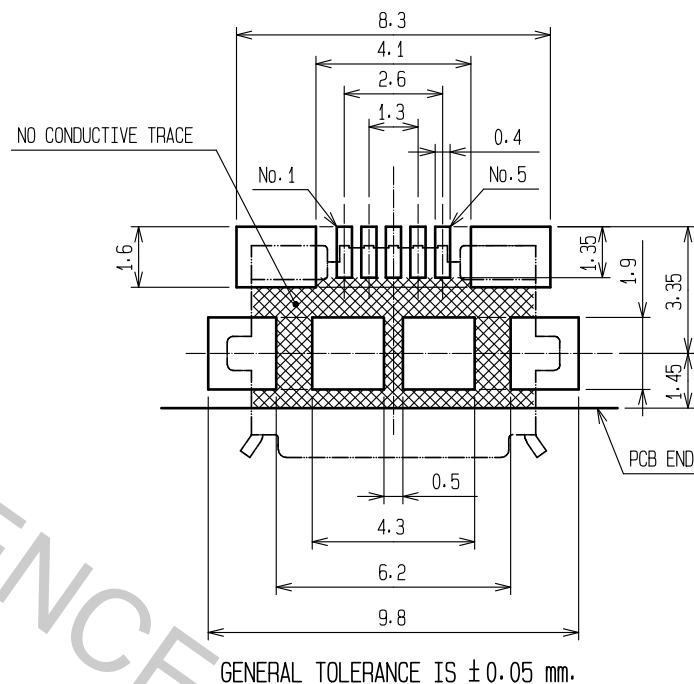




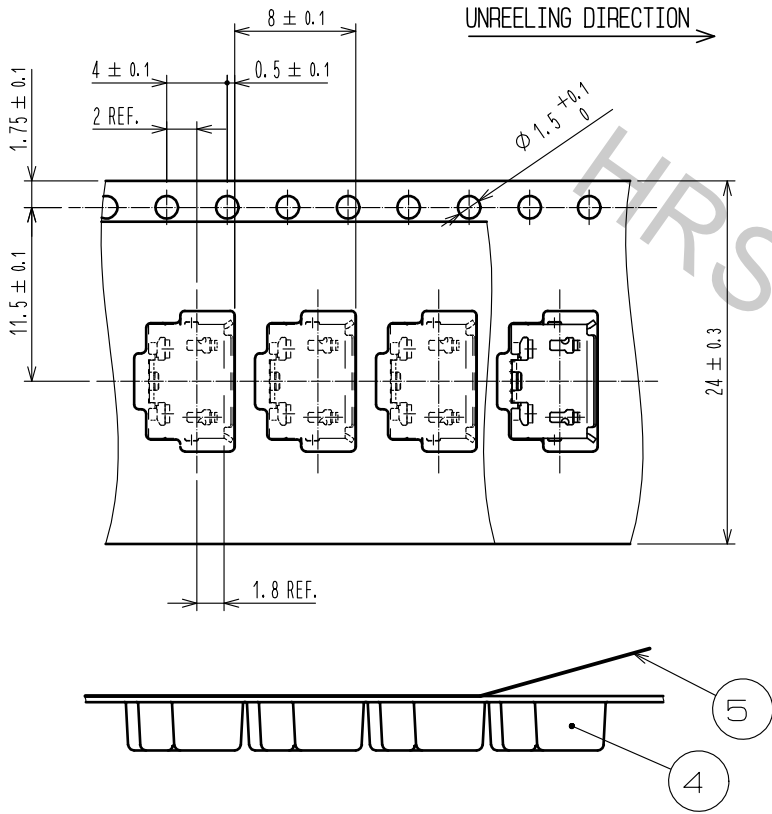
PCB LAYOUT



- NOTES 1 CO-PLANARITY IS WITHIN 0.08 mm.
- 2 PLATING
- CONTACT AREA : GOLD 0.75μm min.
- LEAD AREA : GOLD 0.05μm min.
- UNDER PLATING: NICKEL 2μm min.
- 3 PER REEL : 3500 pcs.
4. INTERFACE DIMENSIONS CONFORM TO USB2.0 SPECIFICATION.
5. AS FOR PART No.3, THE PERFORMANCE REMAINS GOOD EVEN IF THERE ARE RUBBING WOUNDS BY THE ASSEMBLY PROCESS. AND, THE PERFORMANCE REMAINS GOOD THOUGH THERE MIGHT BE A DIFFERENCE IN THE PLATING LUSTER BETWEEN EACH PLATING SUBCONTRACT COMPANIES.
6. AS FOR PART No.1 A PART OF SHAPE MAY BECOME DIFFERENT DEPENDING ON THE PRODUCTION METHOD.
- 7 CODE CONFIGURATION IS SHOWN IN FIG.1.

2	COPPER ALLOY	2	3	STAINLESS STEEL	OVER PLATING:TIN 1μm min. LUBRICANT			
1	LCP	GRAY. UL94V-0						
NO.	MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS		
UNITS mm		SCALE 5 : 1	COUNT 	DESCRIPTION OF REVISIONS		DESIGNED	CHECKED	DATE
 HIROSE ELECTRIC CO., LTD.			APPROVED :NM. NISHIMATSU 15. 10. 27		DRAWING NO. EDC-126557-31-00			
			CHECKED :KN. ICHIKAWA 15. 10. 27		PART NO. ZX62-AB-5PA(31)			
			DESIGNED :TS. ITO 15. 10. 27		CODE NO. CL242-0045-7-31			
			DRAWN :AK. AKIYAMA 15. 10. 27		 1/			

3 DRAWING FOR PACKING (FREE)



7 FIG-1 LOT CODE CONFIGURATIONS FOR 4 DIGITS

YEAR		MONTH		DAY						LINE No.	
YEAR	CODE	MONTH	CODE	DAY	CODE	DAY	CODE	DAY	CODE	LINE No.	CODE
2007	7	Jan.	A	1	1	11	B	21	M	1	A
2008	8	Feb.	B	2	2	12	C	22	N	2	B
2009	9	Mar.	C	3	3	13	D	23	P	3	C
2010	0	Apr.	D	4	4	14	E	24	Q	4	D
2011	1	May.	E	5	5	15	F	25	R	5	E
		Jun.	F	6	6	16	G	26	S	6	F
		Jul.	G	7	7	17	H	27	T	7	G
		Aug.	H	8	8	18	J	28	U	8	H
		Sep.	I	9	9	19	K	29	V	9	I
		Oct.	J	10	A	20	L	30	W	10	J
		Nov.	K					31	X	11	K
		Dec.	L								